Specification of Thermoelectric Module

TES1-06325

Description

The 63 couples, 30mmx15mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

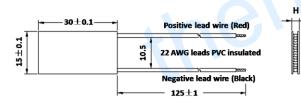
Application

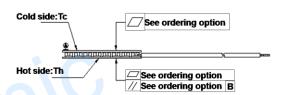
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Peformance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
$\mathrm{DT}_{\mathrm{max}}({}^{\circ}\!\!\mathrm{C})$	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	8.0	8.4	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	2.8	2.8	DC current through the modules at DT _{max}	
Q _{C max} (Watts)	13.8	15.3	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	2.15	2.31	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters





Manufacturing Options

A. Solder:

- 1. T100: BiSn (Tmelt=138℃)
- 2. T200: CuSn (Tmelt = 227 °C)

B. Sealant:

- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

C. Ceramics:

- 1. Alumina (Al₂O₃, white 96%)
- 2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

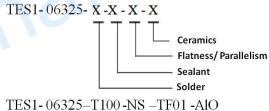
- 1. Blank ceramics (not metallized)
- 2. Metallized (Au plating)

Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)
	H (mm)	Parallelism (mm)	Standard/Optional length
TF	0:4.0± 0.1	0: 0.1/0.13	125±1/Specify
TF	1:4.0 ± 0.05	1: 0.08/0.1	125±1/Specify
TF	2:4.0 ± 0.025	2: 0.05/0.08	125±1/Specify

Eg. TF01: Thickness 4.0± 0.1 (mm) and Flatness 0.08/0.1 (mm)

Naming for the Module



T100: BiSn(Tmelt=138°C)

NS: No sealing AlO: Alumina, white 96%

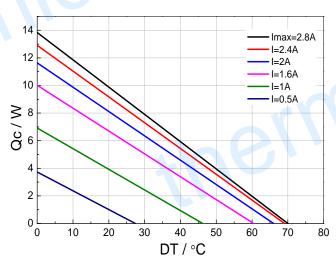
TF01: Thickness ± 0.1 (mm) and Flatness/Parallelism 0.08/0.1 (mm)

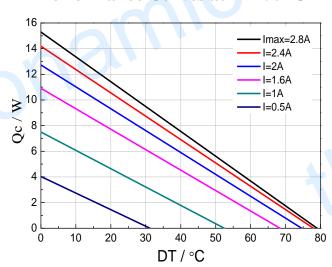
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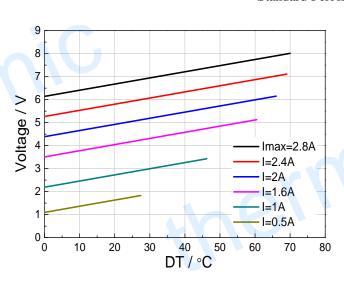
Performance Curves at Th=27 ℃

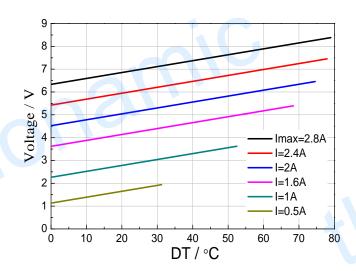
Performance Curves at Th=50 ℃



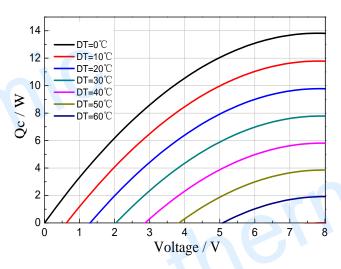


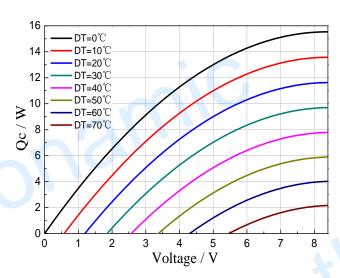
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





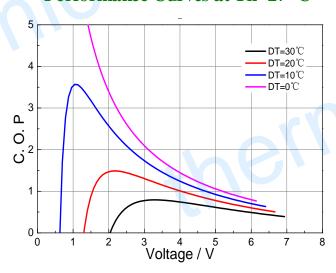
Standard Performance Graph Qc = f(V)

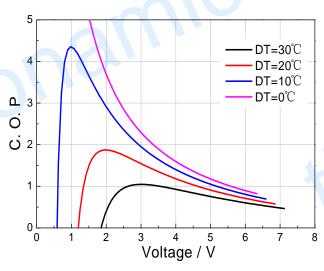
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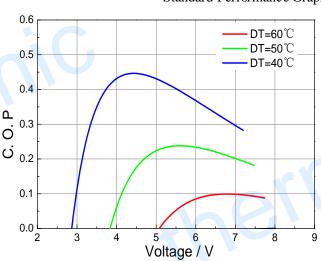
Performance Curves at Th=27 ℃

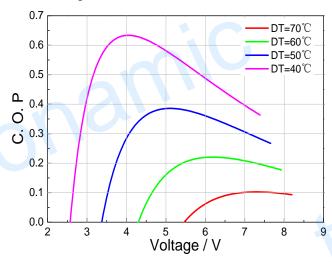
Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Caution

- Cold side of the module sticked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.